

Global 3D IC Market 2012-2016

Description: TechNavio's analysts forecast the Global 3D IC market to grow at a CAGR of 19.7 percent over the period 2012-2016. One of the key factors contributing to this market growth is the huge demand for memory-enhanced applications. The Global 3D IC market has also been witnessing the increase of multi-chip packaging. However, the thermal conductivity issues could pose a challenge to the growth of this market.

TechNavio's report, the Global 3D IC Market 2012-2016, has been prepared based on an in-depth market analysis with inputs from industry experts. The report covers the Americas, and the EMEA and APAC regions; it also covers the Global 3D IC market landscape and its growth prospects in the coming years. The report also includes a discussion of the key vendors operating in this market.

The key vendors dominating this market space are Advanced Semiconductor Engineering Co. (ASE), Samsung Electronics Co. Ltd., STMicroelectronics N.V., and Taiwan Semiconductor Manufacturing Co. Ltd. (TSMC).

The other vendors mentioned in the report are Elpida Memory Inc., IBM Corp., Intel Corp., and Micron Technology Inc.

Key questions answered in this report:

- What will the market size be in 2016 and what will the growth rate be?
- What are the key market trends?
- What is driving this market?
- What are the challenges to market growth?
- Who are the key vendors in this market space?
- What are the market opportunities and threats faced by the key vendors?
- What are the strengths and weaknesses of the key vendors?

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